PECL* to TTL Translator

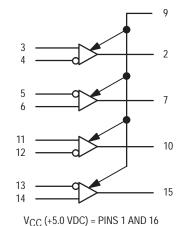
(+5 Vdc Power Supply Only)

The MC10H350 is a member of Motorola's 10H family of high performance ECL logic. It consists of 4 translators with differential inputs and TTL outputs. The 3–state outputs can be disabled by applying a HIGH TTL logic level on the common OE input.

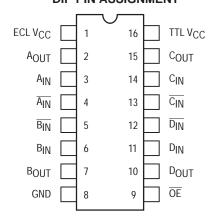
The MC10H350 is designed to be used primarily in systems incorporating both ECL and TTL logic operating off a common power supply. The separate V_{CC} power pins are not connected internally and thus isolate the noisy TTL V_{CC} runs from the relatively quiet ECL V_{CC} runs on the printed circuit board. The differential inputs allow the H350 to be used as an inverting or noninverting translator, or a differential line receiver. The H350 can also drive CMOS with the addition of a pullup resistor.

- Propagation Delay, 3.5 ns Typical
- MECL 10K-Compatible

LOGIC DIAGRAM



GND = PIN 8 **DIP PIN ASSIGNMENT**



Pin assignment is for Dual–in–Line Package.
For PLCC pin assignment, see the Pin Conversion Tables on page 18 of the ON Semiconductor MECL Data Book (DL122/D).



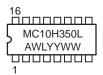
ON Semiconductor

http://onsemi.com

MARKING DIAGRAMS



CDIP-16 L SUFFIX CASE 620





PDIP-16 P SUFFIX CASE 648





PLCC-20 FN SUFFIX CASE 775



A = Assembly Location

WL = Wafer Lot YY = Year WW = Work Week

ORDERING INFORMATION

Device	Package	Shipping
MC10H350L	CDIP-16	25 Units/Rail
MC10H350P	PDIP-16	25 Units/Rail
MC10H350FN	PLCC-20	46 Units/Rail

MAXIMUM RATINGS

Symbol	Characteristic	Rating	Unit
Vcc	Power Supply (VEE = Gnd)	7.0	Vdc
TA	Operating Temperature Range	0 to +75	°C
T _{stg}	Storage Temperature Range – Plastic – Ceramic	−55 to +150 −55 to +165	°C °C

ELECTRICAL CHARACTERISTICS ($V_{CC} = 5.0 \text{ V} \pm 5\%$) (See Note 1.)

			T _A = 0°0		
Symbol	Characteristic	;	Min	Max	Unit
ICC	Power Supply Current	TTL ECL	_ _	20 12	mA
I _I IH	Input Current High	Pin 9 Others	_ _	20 50	μА
I _{IL} I _{INL}	Input Current Low	Pin 9 Others		-0.6 50	mA μA
V_{IH}	Input Voltage High	Pin 9	2.0	-	Vdc
V _{IL}	Input Voltage Low	Pin 9	-	0.8	Vdc
VDIFF	Differential Input Voltage (Note 1.)	Pins 3–6, 11–14 (1)	350	-	mV
VCM	Voltage Common Mode	Pins 3–6, 11–14	2.8	Vcc	Vdc
VOH	Output Voltage High IOH = 3.0 mA		2.7	-	Vdc
VOL	Output Voltage Low IOL = 20 mA		-	0.5	Vdc
los	Short Circuit Current VOUT = 0 V		-60	-150	mA
lozh	Output Disable Current High VOUT = 2.7 V		-	50	μА
lozL	Output Disable Current Low VOUT = 0.5 V		-	-50	μА

^{1.} Common mode input voltage to pins 3-4, 5-6, 11-12, 13-14 must be between the values of 2.8 V and 5.0 V. This common mode input voltage range includes the differential input swing.

 $^{2. \ \ \}text{For single ended use, apply 3.75 V (V}_{BB}) \ \text{to either input depending on output polarity required. Signal level range to other input is 3.3 V to 4.2 V.}$

^{3.} Any unused gates should have the inverting inputs tied to V_{CC} and the non–inverting inputs tied to ground to prevent output glitching.

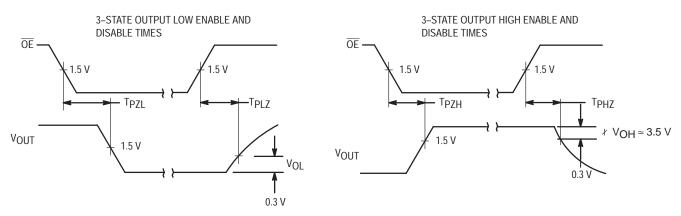
^{4. 1.0} V to 2.0 V w/50 pF into 500 ohms.

^{*}Positive Emitter Coupled Logic

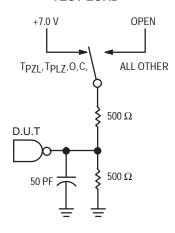
ELECTRICAL CHARACTERISTICS (V_{CC} = 5.0 V ±5%) (See Notes 1 & 4)

		T _A = 0°C to 75°C		
Symbol	Characteristic	Min	Max	Unit
AC PARAMETERS ($C_L = 50 \text{ pF}$) ($V_{CC} = 5.0 \pm 5\%$) ($T_A = 0^{\circ}\text{C}$ to 75°C)				
tpd	Propagation Delay Data (50% to 1.5V)	1.5	5.0	ns
t _r	Rise Time (Note 4.)	0.3	1.6	ns
t _f	Fall Time (Note 4.)	0.3	1.6	ns
^t pdLZ ^t pdHZ	Output Disable Time	2.0 2.0	6.0 6.0	ns
^t pdZL ^t pdZH	Output Enable Time	2.0 2.0	8.0 8.0	ns

3-STATE SWITCHING WAVEFORMS



TEST LOAD

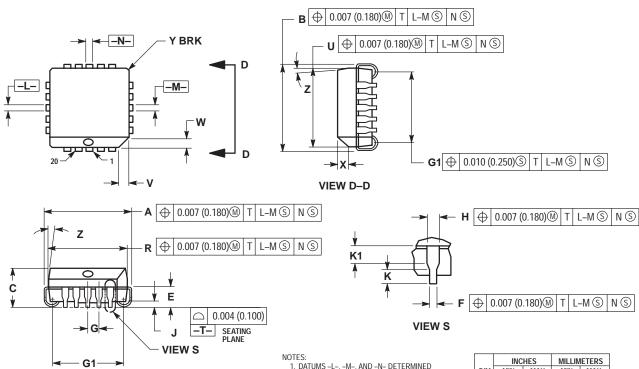


*INCLUDES JIG AND PROBE CAPACITANCE

Application Note: Pin 9 is an $\overline{\text{OE}}$ and the 10H350 is disabled when $\overline{\text{OE}}$ is at V_{IH} or higher.

PACKAGE DIMENSIONS

PLCC-20 **FN SUFFIX** PLASTIC PLCC PACKAGE CASE 775-02 **ISSUE C**



⊕ 0.010 (0.250)⑤ T L-M ⑤ N ⑤

- WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.
- 2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.

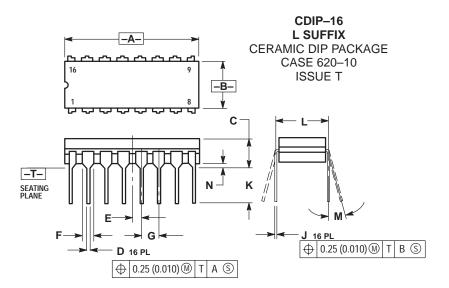
 3. DIMENSIONS R AND U DO NOT INCLUDE MOLD.
- FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.

 4. DIMENSIONING AND TOLERANCING PER ANSI
- 4. DIMENSIONING AND TOLERANCING FER ANSI Y14.5M, 1982. 5. CONTROLLING DIMENSION: INCH. 6. THE PACKAGE TOP MAY BE SMALLER THAN THE
- PACKAGE BOTTOM BY UP TO 0.012 (0.300).
 DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP
- INCLUDING ANY MISMAICH BE I WEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.

 7. DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.385	0.395	9.78	10.03
В	0.385	0.395	9.78	10.03
С	0.165	0.180	4.20	4.57
Ε	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050	BSC	1.27	BSC
Н	0.026	0.032	0.66	0.81
J	0.020		0.51	
K	0.025		0.64	
R	0.350	0.356	8.89	9.04
U	0.350	0.356	8.89	9.04
٧	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
Χ	0.042	0.056	1.07	1.42
Υ		0.020		0.50
Z	2°	10°	2°	10°
G1	0.310	0.330	7.88	8.38
K1	0.040		1.02	

PACKAGE DIMENSIONS

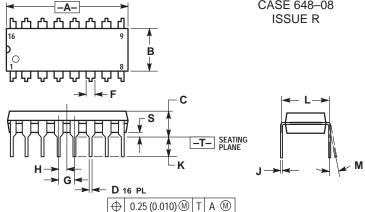


- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
 4. DIMENSION F MAY NARROW TO 0.76 (0.030) WHERE THE LEAD ENTERS THE CERAMIC BODY.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.750	0.785	19.05	19.93
В	0.240	0.295	6.10	7.49
С		0.200		5.08
D	0.015	0.020	0.39	0.50
Ε	0.050 BSC		1.27 BSC	
F	0.055	0.065	1.40	1.65
G	0.100 BSC		2.54 BSC	
Н	0.008	0.015	0.21	0.38
K	0.125	0.170	3.18	4.31
L	0.300 BSC		7.62 BSC	
M	0°	15°	0°	15°
N	0.020	0.040	0.51	1.01

PDIP-16 **P SUFFIX**

PLASTIC DIP PACKAGE CASE 648-08 ISSUE R



- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: INCH.

 3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.

 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

 5. ROUNDED CORNERS OPTIONAL.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.740	0.770	18.80	19.55
В	0.250	0.270	6.35	6.85
С	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
Н	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10 °	0 °	10 °
S	0.020	0.040	0.51	1.01

Notes

Notes

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